

□ Assembly Process efficiency. There is no change in data sheet parameters. □ Equipment □ Material □ Testing □ Manufacturing Site □ Data Sheet □ Other					
Contact: Bimla Paul Title: Quality Assurance Manager Attachment: Yes Phone #: (408)-574-6419 Fax #: (408)-284-8362 Samples: Available upon request E-mail: bimla.paul@idt.com DESCRIPTION AND PURPOSE OF CHANGE: Die Technology Wafer Fabrication Process Product stepping changes from "Y" to "YB" to improve man Assembly Process efficiency. There is no change in data sheet parameters. Equipment Material Testing Manufacturing Site Data Sheet Other					
Title: Quality Assurance Manager Phone #: (408)-574-6419 Fax #: (408)-284-8362 E-mail: bimla.paul@idt.com DESCRIPTION AND PURPOSE OF CHANGE: □ Die Technology □ Wafer Fabrication Process □ Assembly Process □ Equipment □ Material □ Testing □ Manufacturing Site □ Data Sheet □ Other					
Phone #: (408)-574-6419 Fax #: (408)-284-8362 Samples: Available upon request E-mail: bimla.paul@idt.com DESCRIPTION AND PURPOSE OF CHANGE: Die Technology Wafer Fabrication Process Product stepping changes from "Y" to "YB" to improve man Assembly Process efficiency. There is no change in data sheet parameters. Equipment Material Testing Manufacturing Site Data Sheet Other					
Fax #: (408)-284-8362 Samples: Available upon request E-mail: bimla.paul@idt.com DESCRIPTION AND PURPOSE OF CHANGE: Die Technology Wafer Fabrication Process Product stepping changes from "Y" to "YB" to improve man efficiency. There is no change in data sheet parameters. Equipment Material Testing Manufacturing Site Data Sheet Other	☐ No				
E-mail: bimla.paul@idt.com DESCRIPTION AND PURPOSE OF CHANGE: Die Technology Wafer Fabrication Process Product stepping changes from "Y" to "YB" to improve man efficiency. There is no change in data sheet parameters. Equipment Material Testing Manufacturing Site Data Sheet Other					
DESCRIPTION AND PURPOSE OF CHANGE: □ Die Technology □ Wafer Fabrication Process Product stepping changes from "Y" to "YB" to improve man □ Assembly Process efficiency. There is no change in data sheet parameters. □ Equipment □ Material □ Testing □ Manufacturing Site □ Data Sheet □ Other					
 □ Die Technology □ Wafer Fabrication Process □ Assembly Process □ Equipment □ Material □ Testing □ Manufacturing Site □ Data Sheet ■ Other 					
□ Die Technology □ Wafer Fabrication Process □ Assembly Process □ Equipment □ Material □ Testing □ Manufacturing Site □ Data Sheet □ Other RELIABILITY/QUALIFICATION SUMMARY: Please see the attachment for reliability data. CUSTOMER ACKNOWLEDGMENT OF RECEIPT: IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable. IDT reserves the right to ship either version manufactured after the process change effective date until the inventory					
on the earlier version has been depleted.					
Customer: Approval for shipments prior to	o effective date.				
Name/Date: E-Mail Address:					
Title: Phone# /Fax# :					
CUSTOMER COMMENTS:					
IDT ACKNOWLEDGMENT OF RECEIPT:					
RECD. BY: DATE:					



Integrated Device Technology, Inc. 6024 Silver Creek Valley Road, San Jose, CA 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: T0512-01

PCN Type: Product Stepping Change

Data Sheet Change: None

Detail of Change: Product stepping changes from "Y" to "YB" to improve manufacturing

efficiency. There is no change in data sheet parameters.

Qualification Data: The following reliability tests were performed on 82V2088 DR208 (208-pin PQFP)

Qualification results are as follow:

Test Description	Test Method	Required Sample/# Fails	Test results
High Temperature Operating Life Test: Dynamic 1000 hrs @ 125°C	JESD22-A108	77/0	77/0
Highly Accelerated Stress Test (HAST): 130°C/85%R.H. Static Bias for 100 hours	EIA/JESD22- A100	45/0	45/0
Autoclave (Steam Pressure Pot), 168hrs @ 2 ATM, Saturated Steam @ 121°C	EIA/JESD22- A102	45/0	45/0
Temperature Cycle (T/C), -65°C/ 150°C for 500 cycles	JESD22-A104	45/0	45/0
ESD Human Body Model	Mil-Std 883 Method 3015	3/0	2,000V
ESD Charged Device Model	JEDEC 22-101	3/0	500V
Latch-up	EIA/JESD STD-78	10/0	10/0